Electronic Acknowledgement Receipt				
EFS ID:	1318054			
Application Number:	10809182			
International Application Number:				
Confirmation Number:	6820			
Title of Invention:	Resin composition for encapsulating semiconductor chip and semiconductor device therewith			
First Named Inventor/Applicant Name:	Kuniharu Umeno			
Customer Number:	25461			
Filer:	Robert G. Weilacher/Susan Revell			
Filer Authorized By:	Robert G. Weilacher			
Attorney Docket Number:	033036.076			
Receipt Date:	16-NOV-2006			
Filing Date:	25-MAR-2004			
Time Stamp:	14:54:18			
Application Type:	Utility			

Payment information:

Submitted with Payment	no	
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Supplemental Response or Supplemental Amendment	33036-076.PDF	147708	no	4
Warnings:					

Information:	
Total Files Size (in bytes):	147708

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.